

FIG. 1a

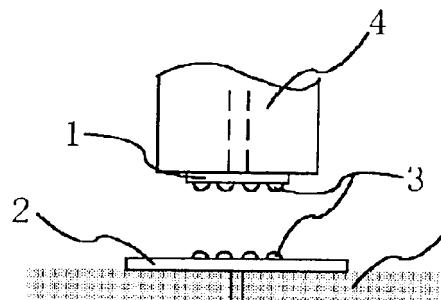


FIG. 1b

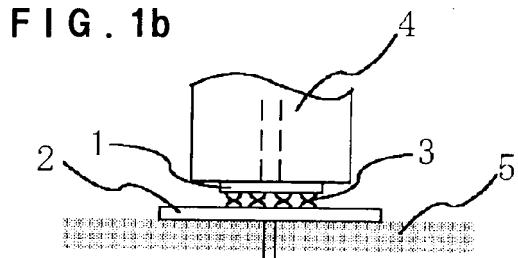


FIG. 1c

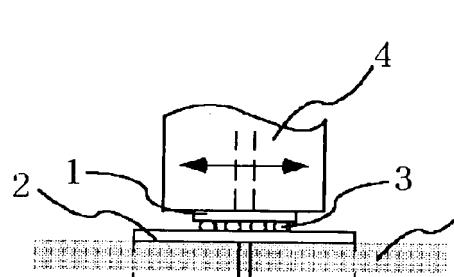


FIG. 1e

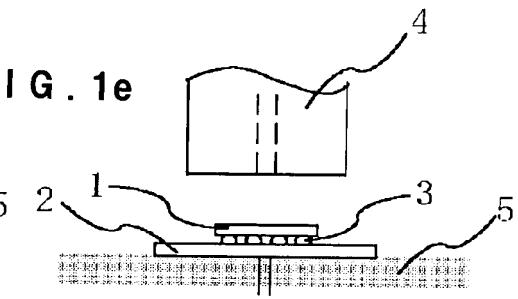
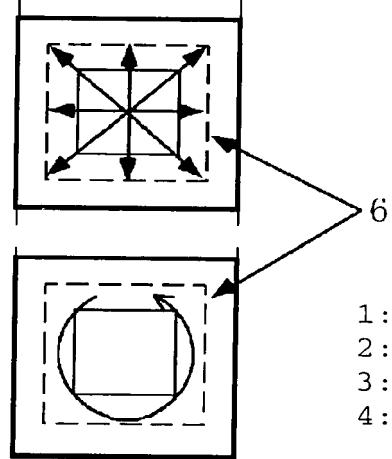


FIG. 1d



- 1: semiconductor element
- 2: wiring board
- 3: solder bump
- 4: ultrasonic bonding head

FIG. 2

